

## Quad 2-Input Multiplexer with Three-State Outputs

### Features

- 'AC257, 'ACT257..... Non-Inverting Outputs
  - CD74ACT258 ..... Inverting Outputs
  - Buffered Inputs
  - Typical Propagation Delay
    - 4.4ns at  $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ ,  $C_L = 50pF$
  - Exceeds 2kV ESD Protection MIL-STD-883, Method 3015
  - SCR-Latchup-Resistant CMOS Process and Circuit Design
  - Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption
  - Balanced Propagation Delays
  - AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
  - $\pm 24mA$  Output Drive Current
    - Fanout to 15 FAST™ ICs
- Drives 50 $\Omega$  Transmission Lines

### Description

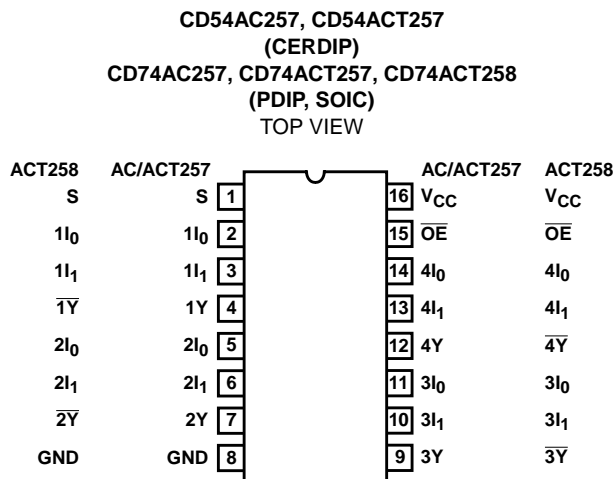
The 'AC257, 'ACT257 and CD74ACT258 are quad 2-input multiplexers with three-state outputs that utilize Advanced CMOS Logic technology. Each of these devices selects four bits of data from two sources under the control of a common Select input (S). The Output Enable ( $\overline{OE}$ ) is active LOW. When  $\overline{OE}$  is HIGH, all of the outputs (Y or  $\overline{Y}$ ) are in the high-impedance state regardless of all other input conditions.

Moving data from two groups of registers to four common output buses is a common use of the 'AC257, 'ACT257, and CD74ACT258. The state of the Select input determines the particular register from which the data comes. The 'AC257, 'ACT257 and CD74ACT258 can also be used as function generators.

### Ordering Information

PART NUMBER	TEMP. RANGE ( $^{\circ}C$ )	PACKAGE
CD54AC257F3A	-55 to 125	16 Ld CERDIP
CD74AC257E	0 to 70 $^{\circ}C$ , -40 to 85, -55 to 125	16 Ld PDIP
CD74AC257M	0 to 70 $^{\circ}C$ , -40 to 85, -55 to 125	16 Ld SOIC
CD54ACT257F3A	-55 to 125	16 Ld CERDIP
CD74ACT257E	0 to 70 $^{\circ}C$ , -40 to 85, -55 to 125	16 Ld PDIP
CD74ACT257M	0 to 70 $^{\circ}C$ , -40 to 85, -55 to 125	16 Ld SOIC
CD74ACT258E	0 to 70 $^{\circ}C$ , -40 to 85, -55 to 125	16 Ld PDIP
CD74ACT258M	0 to 70 $^{\circ}C$ , -40 to 85, -55 to 125	16 Ld SOIC

### Pinout

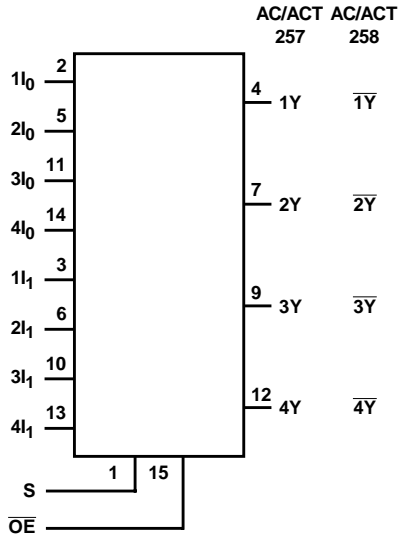


#### NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local TI sales office or customer service for ordering information.

**CD54/74AC257, CD54/74ACT257, CD74ACT258**

**Functional Diagram**



**TRUTH TABLE**

OUTPUT ENABLE	SELECT INPUT	DATA INPUTS		257 OUTPUTS	258 OUTPUTS
$\overline{OE}$	S	$I_0$	$I_1$	Y	$\overline{Y}$
H	X	X	X	Z	Z
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L

H = High level voltage, L = Low level voltage, Z = High impedance (off) state, X = Don't Care

## CD54/74AC257, CD54/74ACT257, CD74ACT258

### Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 6V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 50mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 50mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ (Note 3) .....	$\pm 100mA$

### Thermal Information

Thermal Resistance (Typical, Note 5)	$\theta_{JA}$ ( $^{\circ}C/W$ )
PDIP Package .....	—
SOIC Package .....	—
Maximum Junction Temperature (Plastic Package) .....	$150^{\circ}C$
Maximum Storage Temperature Range .....	$-65^{\circ}C$ to $150^{\circ}C$
Maximum Lead Temperature (Soldering 10s) .....	$300^{\circ}C$

### Operating Conditions

Temperature Range, $T_A$ .....	$-55^{\circ}C$ to $125^{\circ}C$
Supply Voltage Range, $V_{CC}$ (Note 4)	
AC Types .....	1.5V to 5.5V
ACT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Slew Rate, $dt/dv$	
AC Types, 1.5V to 3V .....	50ns (Max)
AC Types, 3.6V to 5.5V .....	20ns (Max)
ACT Types, 4.5V to 5.5V .....	10ns (Max)

*CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.*

#### NOTES:

3. For up to 4 outputs per device, add  $\pm 25mA$  for each additional output.
4. Unless otherwise specified, all voltages are referenced to ground.
5.  $\theta_{JA}$  is measured with the component mounted on an evaluation PC board in free air.

### DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25 $^{\circ}C$		-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS
		$V_I$ (V)	$I_O$ (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
<b>AC TYPES</b>											
High Level Input Voltage	$V_{IH}$	-	-	1.5	1.2	-	1.2	-	1.2	-	V
				3	2.1	-	2.1	-	2.1	-	V
				5.5	3.85	-	3.85	-	3.85	-	V
Low Level Input Voltage	$V_{IL}$	-	-	1.5	-	0.3	-	0.3	-	0.3	V
				3	-	0.9	-	0.9	-	0.9	V
				5.5	-	1.65	-	1.65	-	1.65	V
High Level Output Voltage	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	3	2.58	-	2.48	-	2.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V

**CD54/74AC257, CD54/74ACT257, CD74ACT258**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Three-State Leakage Current	I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND	-	5.5	-	±0.5	-	±5	-	±10	µA
Quiescent Supply Current MSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	8	-	80	-	160	µA
<b>ACT TYPES</b>											
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	5.5	-	±0.1	-	±1	-	±1	µA
Three-State or Leakage Current	I <sub>OZ</sub>	V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND	-	5.5	-	±0.5	-	±5	-	±10	µA
Quiescent Supply Current MSI	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	8	-	80	-	160	µA
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

**NOTES:**

- Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
- Test verifies a minimum 50Ω transmission-line-drive capability at 85°C, 75Ω at 125°C.

**CD54/74AC257, CD54/74ACT257, CD74ACT258**

**ACT Input Load Table**

INPUT	UNIT LOAD
Data	0.83
S	1.27
OE	1.27

NOTE: Unit load is  $\Delta I_{CC}$  limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

**Switching Specifications** Input  $t_r$ ,  $t_f = 3ns$ ,  $C_L = 50pF$  (Worst Case)

PARAMETER	SYMBOL	$V_{CC}$ (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
<b>ACT TYPES</b>									
Propagation Delay, In to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	106	-	-	117	ns
		3.3 (Note 9)	3.3	-	11.8	3.3	-	13	ns
		5 (Note 10)	2.4	-	8.5	2.3	-	9.3	ns
Propagation Delay, S to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	153	-	-	168	ns
		3.3	4.8	-	17.1	4.7	-	18.8	ns
		5	3.5	-	12.2	3.4	-	13.4	ns
Propagation Delay, OE to Y AC/ACT257	$t_{PLZ}$ , $t_{PHZ}$ , $t_{PZL}$ , $t_{PZH}$	1.5	-	-	167	-	-	184	ns
		3.3	5.3	-	18.7	5.2	-	20.6	ns
		5	3.8	-	13.4	3.7	-	14.7	ns
Propagation Delay, In to Y 'AC/CD74ACT258	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	91	-	-	100	ns
		3.3	2.9	-	10.2	2.8	-	11.2	ns
		5	2.1	-	7.3	2	-	8	ns
Propagation Delay, S to Y 'AC/CD74ACT258	$t_{PLH}$ , $t_{PHL}$	1.5	-	-	153	-	-	168	ns
		3.3	4.8	-	17.1	4.7	-	18.8	ns
		5	3.5	-	12.2	3.4	-	13.4	ns
Propagation Delay, OE to Y 'AC/CD74ACT258	$t_{PLZ}$ , $t_{PHZ}$ , $t_{PZL}$ , $t_{PZH}$	1.5	-	-	167	-	-	184	ns
		3.3	5.3	-	18.7	5.2	-	20.6	ns
		5	3.8	-	13.4	3.7	-	14.7	ns
Three-State Output Capacitance	$C_O$	-	-	-	15	-	-	15	pF
Input Capacitance	$C_I$	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	$C_{PD}$ (Note 11)	-	-	130	-	-	130	-	pF
<b>ACT TYPES</b>									
Propagation Delay, In to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	5 (Note 10)	2.8	-	9.7	2.7	-	10.7	ns
Propagation Delay, S to Y AC/ACT257	$t_{PLH}$ , $t_{PHL}$	5	4	-	14	3.9	-	15.4	ns

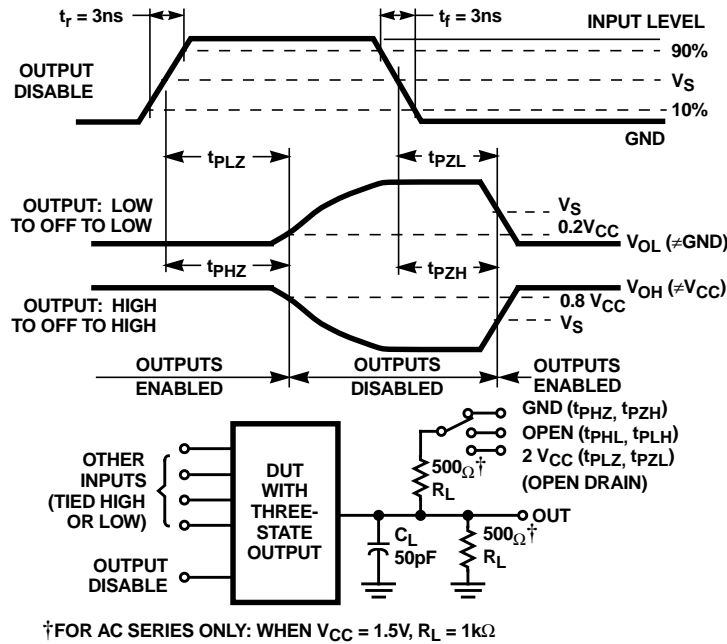
## CD54/74AC257, CD54/74ACT257, CD74ACT258

### Switching Specifications Input $t_r, t_f = 3\text{ns}$ , $C_L = 50\text{pF}$ (Worst Case) (Continued)

PARAMETER	SYMBOL	$V_{CC}$ (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
Propagation Delay, $\overline{\text{OE}}$ to Y AC/ACT257	$t_{PLZ}, t_{PHZ}, t_{PZL}, t_{PZH}$	5	4.1	-	14.6	4	-	16.1	ns
Propagation Delay, In to Y 'AC/CD74ACT258	$t_{PLH}, t_{PHL}$	5	2.4	-	8.5	2.3	-	9.3	ns
Propagation Delay, S to Y 'AC/CD74ACT258	$t_{PLH}, t_{PHL}$	5	4	-	14	3.9	-	15.4	ns
Propagation Delay, $\overline{\text{OE}}$ to Y 'AC/CD74ACT258	$t_{PLZ}, t_{PHZ}, t_{PZL}, t_{PZH}$	5	4.1	-	14.6	4	-	16.1	ns
Three-State Output Capacitance	$C_O$	-	-	-	15	-	-	15	pF
Input Capacitance	$C_I$	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	$C_{PD}$ (Note 11)	-	-	130	-	-	130	-	pF

**NOTES:**

8. Limits tested 100%.
9. 3.3V Min is at 3.6V, Max is at 3V.
10. 5V Min is at 5.5V, Max is at 4.5V.
11.  $C_{PD}$  is used to determine the dynamic power consumption per multiplexer.  
 AC:  $P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o)$   
 ACT:  $P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o) + V_{CC} \Delta I_{CC}$  where  $f_i$  = input frequency,  $f_o$  = output frequency,  $C_L$  = output load capacitance,  $V_{CC}$  = supply voltage.



**FIGURE 1. THREE-STATE PROPAGATION DELAY TIMES AND TEST CIRCUIT**

CD54/74AC257, CD54/74ACT257, CD74ACT258

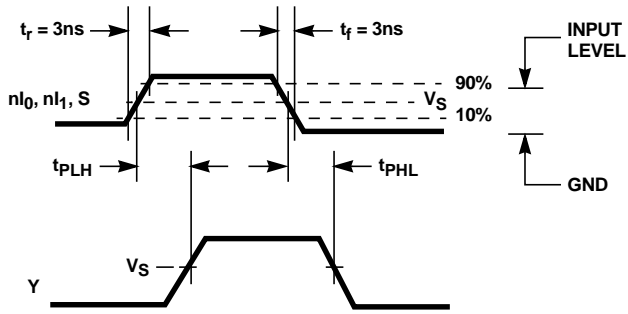


FIGURE 2. INPUTS OR SELECT TO OUTPUT PROPAGATION DELAYS (AC/ACT257)

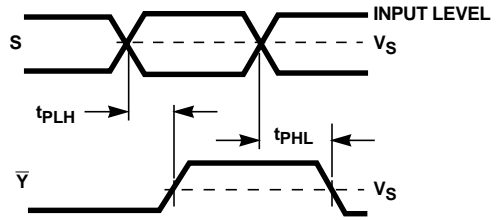
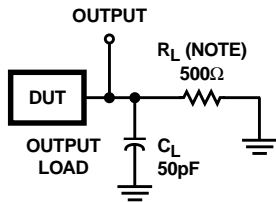


FIGURE 3. SELECT TO OUTPUT PROPAGATION DELAYS (CD74ACT258)



NOTE: For AC Series Only: When  $V_{CC} = 1.5V$ ,  $R_L = 1k\Omega$ .

	AC	ACT
Input Level	$V_{CC}$	3V
Input Switching Voltage, $V_S$	$0.5 V_{CC}$	1.5V
Output Switching Voltage, $V_S$	$0.5 V_{CC}$	$0.5 V_{CC}$

FIGURE 4. PROPAGATION DELAY TIMES

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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54AC257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD54ACT257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD74AC257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC257EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT257EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74ACT257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74ACT258M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CD74ACT258MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT258M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

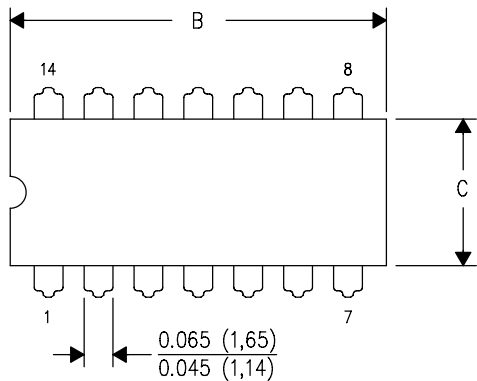


\*All dimensions are nominal

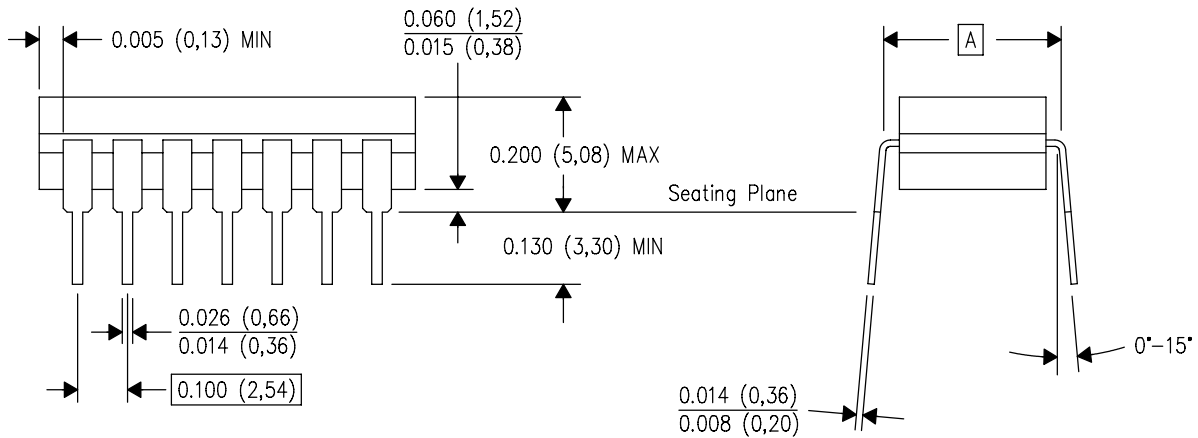
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT257M96	SOIC	D	16	2500	346.0	346.0	33.0
CD74ACT257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT258M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

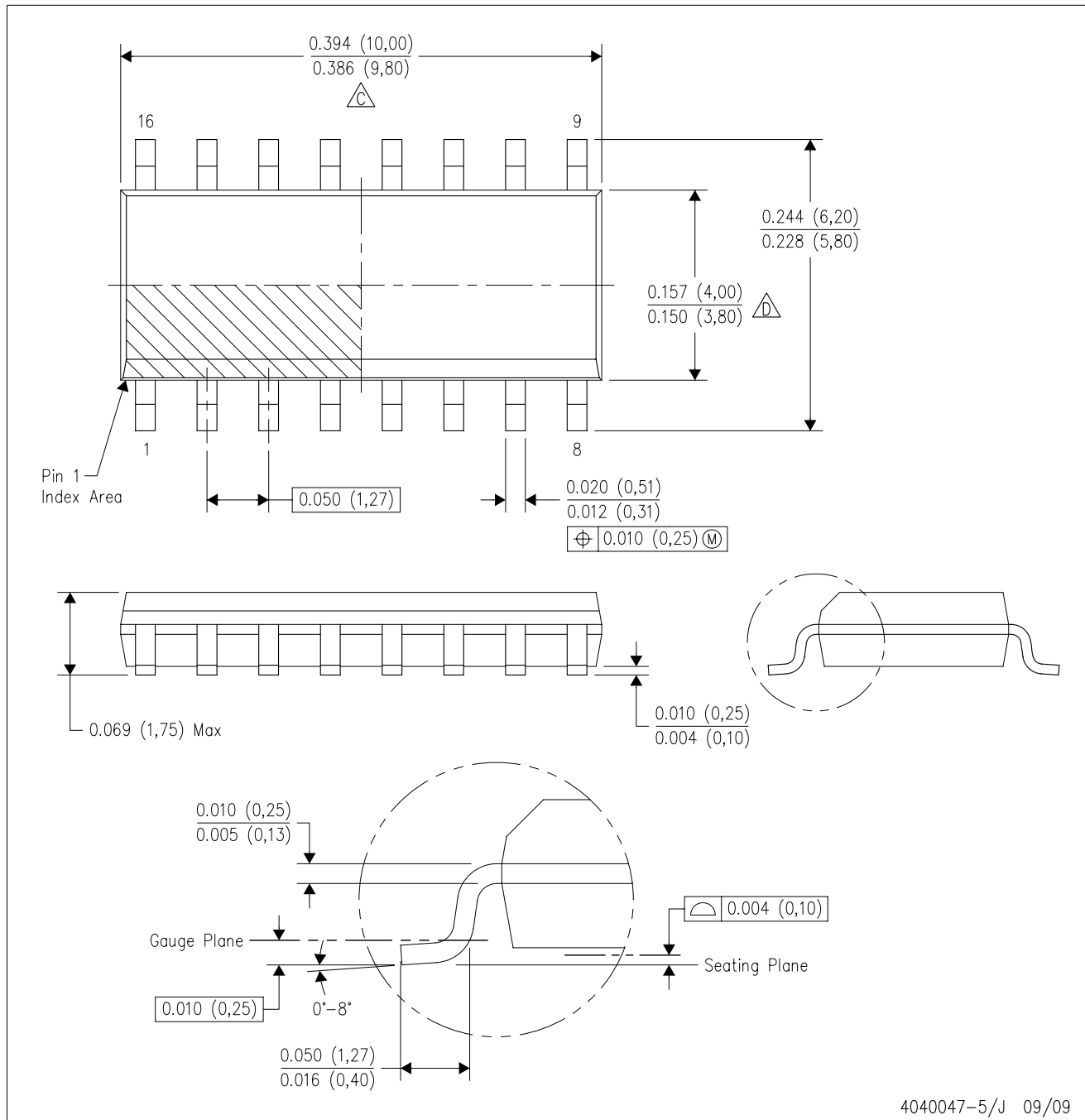


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-5/J 09/09

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



4209373/A 03/08

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD54AC257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54AC257F3A	<a href="#">Samples</a>
CD54ACT257F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54ACT257F3A	<a href="#">Samples</a>
CD74AC257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC257E	<a href="#">Samples</a>
CD74AC257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC257M	<a href="#">Samples</a>
CD74AC257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC257M	<a href="#">Samples</a>
CD74AC257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC257M	<a href="#">Samples</a>
CD74ACT257E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT257E	<a href="#">Samples</a>
CD74ACT257EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT257E	<a href="#">Samples</a>
CD74ACT257M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT257M	<a href="#">Samples</a>
CD74ACT257M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT257M	<a href="#">Samples</a>
CD74ACT257M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT257M	<a href="#">Samples</a>
CD74ACT257MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT257M	<a href="#">Samples</a>
CD74ACT258M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-55 to 125	ACT258M	<a href="#">Samples</a>
CD74ACT258M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-55 to 125	ACT258M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF CD54AC257, CD54ACT257, CD74AC257, CD74ACT257 :**

● Catalog: [CD74AC257](#), [CD74ACT257](#)

● Military: [CD54AC257](#), [CD54ACT257](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT257M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74ACT258M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT257M96	SOIC	D	16	2500	367.0	367.0	38.0
CD74ACT257M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74ACT258M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
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